

Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$
- ◆ Low FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Advanced GreenMOS™ technology

Applications

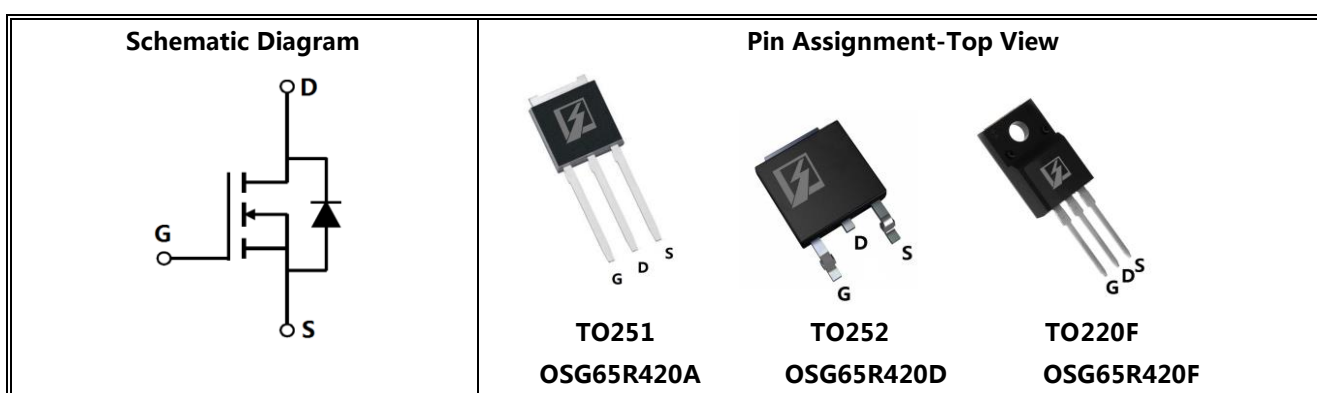
- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Adapter
- ◆ Telecom

■ General Description

OSG65R420x series use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

| | |
|---------------------------|------------|
| ◆ $V_{DS@T_{jmax}}$ | 700V(min) |
| ◆ I_D | 10.5A |
| ◆ $R_{DS(ON)}@V_{GS}=10V$ | 0.42Ω(max) |

■ TO251, TO252, TO220F Package Information



■ Absolute Maximum Ratings ($T_j=25^{\circ}\text{C}$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|---|-------------------|------------|------|
| Drain-Source Voltage | V_{DS} | 650 | V |
| Gate-Source Voltage | V_{GS} | ±30 | V |
| Drain Current-Continuous ^(Note 1) | I_D | 10.5 | A |
| Drain Current- Pulsed ^(Note 2) | I_{DM} | 31.5 | A |
| Power Dissipation ^(Note 3) for TO251, TO252 | P_D | 83 | W |
| Power Dissipation ^(Note 3) for TO220F | | 31 | |
| Single Pulsed-Avalanche Energy ^(Note 6) | E_{AS} | 280 | mJ |
| MOSFET dv/dt Ruggedness | dv/dt | 50 | V/ns |
| Reverse Diode dv/dt, $V_{DS}=0\text{...}400V$, $I_{SD}\sim I_D$, $T_j=25^{\circ}\text{C}$ | dv/dt | 15 | V/ns |
| Operation and Storage Junction Temperature | T_{stg} , T_j | -55 to 150 | °C |

■ Thermal Characteristics

| Parameter | Symbol | Value | | Unit |
|--|-----------------|-------------|--------|-----------------------------|
| | | TO251/TO252 | TO220F | |
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 1.5 | 4 | $^{\circ}\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Ambient (Note 4) | $R_{\theta JA}$ | 62 | 62.5 | $^{\circ}\text{C}/\text{W}$ |

■ Electrical Characteristics ($T_j=25^{\circ}\text{C}$ unless otherwise noted)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|----------------------------------|--------------|------|------|------|---------------|---|
| Drain-Source Breakdown Voltage | BV_{DSS} | 650 | | | V | $V_{GS}=0\text{V}, I_D=250\mu\text{A}$ |
| | | 700 | 764 | | | $V_{GS}=0\text{V}, I_D=250\mu\text{A}, T_j=150^{\circ}\text{C}$ |
| Gate Threshold Voltage | $V_{GS(th)}$ | 2.0 | | 4.0 | V | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$ |
| Drain-Source On-state Resistance | $R_{DS(on)}$ | | 0.35 | 0.42 | Ω | $V_{GS}=10\text{V}, I_D=5.5\text{A}$ |
| | | | 0.98 | | | $V_{GS}=10\text{V}, I_D=5.5\text{A}, T_j=150^{\circ}\text{C}$ |
| Gate-Source Leakage Current | I_{GSS} | | | 100 | nA | $V_{GS}=30\text{V}$ |
| | | | | -100 | | $V_{GS}=-30\text{V}$ |
| Drain-to-Source Leakage Current | I_{DSS} | | | 1 | μA | $V_{DS}=650\text{V}, V_{GS}=0\text{V}$ |

■ Dynamic Characteristics

| | | | | | | |
|------------------------------|--------------|--|-------|--|----|---|
| Input Capacitance | C_{iss} | | 707.2 | | pF | $V_{GS}=0\text{V}, V_{DS}=50\text{V}, f=1\text{MHZ}$ |
| Output Capacitance | C_{oss} | | 52.2 | | pF | |
| Reverse Transfer Capacitance | C_{rss} | | 2.5 | | pF | |
| Turn-on Delay Time | $t_{d(on)}$ | | 23.7 | | ns | $V_{GS}=10\text{V}, V_{DS}=520\text{V}, R_G=25\Omega, I_D=10.5\text{A}$ |
| Turn-on Rise Time | t_r | | 24.1 | | ns | |
| Turn-Off Delay Time | $t_{d(off)}$ | | 34.1 | | ns | |
| Turn-Off Fall Time | t_f | | 36.8 | | ns | |

■ Gate Charge Characteristics

| | | | | | | |
|--------------------|----------|--|------|--|----|--|
| Total Gate Charge | Q_g | | 14.8 | | nC | $I_D = 10.5A,$ $V_{DS} = 520V,$ $V_{GS} = 10V$ |
| Gate-Source Charge | Q_{gs} | | 3.8 | | nC | |
| Gate-Drain Charge | Q_{gd} | | 5.2 | | nC | |

■ Body Diode Characteristics

| | | | | | | |
|--|-----------|--|-------|------|---------|--|
| Body-diode Forward Current ^(NOTE 2) | I_S | | | 10.5 | A | $V_{GS} < V_{th}$ |
| Pulsed Source Current | I_{SP} | | | 31.5 | | |
| Diode Forward Voltage | V_{SD} | | | 1.4 | V | $I_S = 10.5A, V_{GS} = 0V$ |
| Reverse Recovery Time | t_{rr} | | 277.3 | | ns | $I_S = 10.5A, V_{GS} = 0V$ $di/dt = 100A/\mu s$ |
| Reverse Recovery Charge | Q_{rr} | | 3 | | μC | |
| Peak Reverse Recovery Current | I_{rrm} | | 20.5 | | A | |

■ **Typical Electrical and Thermal Characteristics**

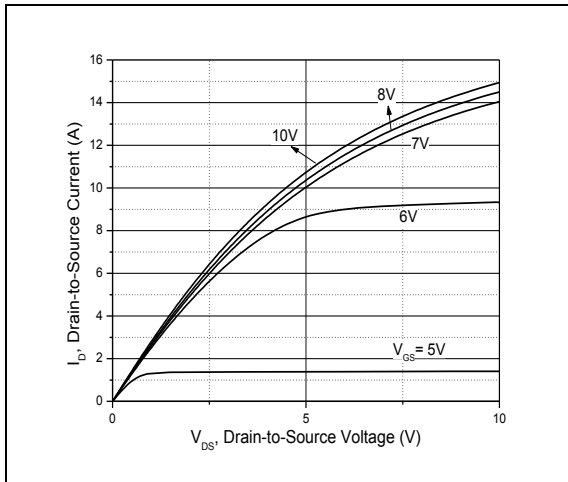


Figure 1. Typ Output Characteristics

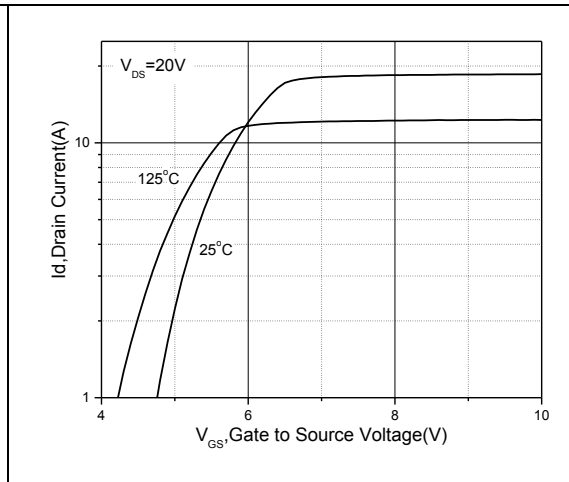


Figure 2. Transfer Characteristics

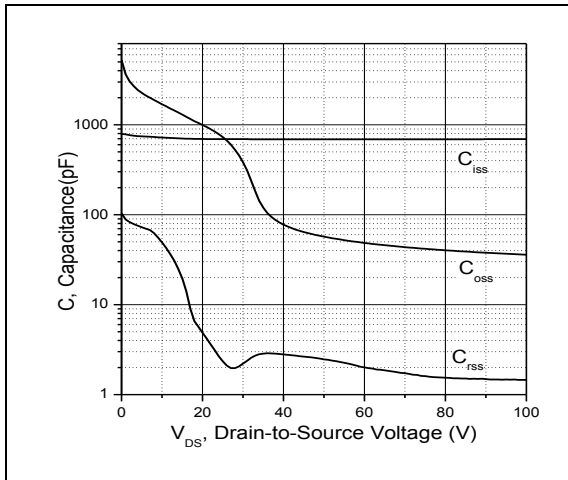


Figure 3. Typ. Capacitance

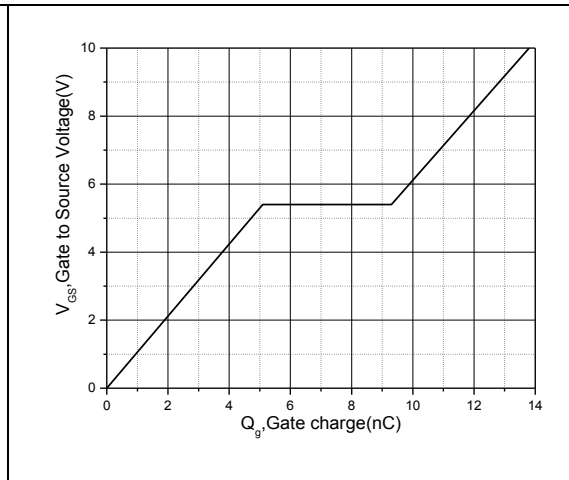


Figure 4. Gate Charge

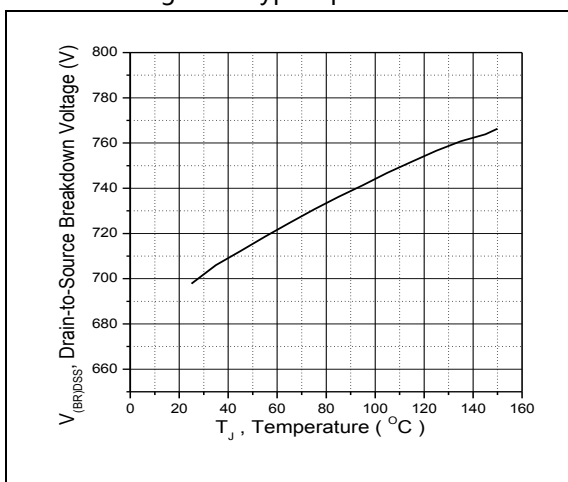


Figure 5. Drain-source breakdown voltage

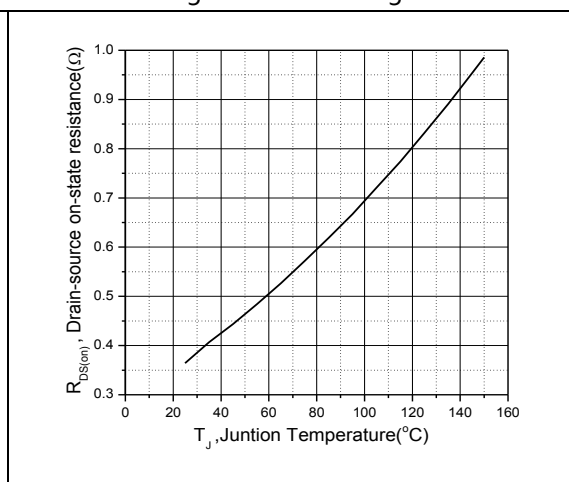


Figure 6. Drain-source on-resistance

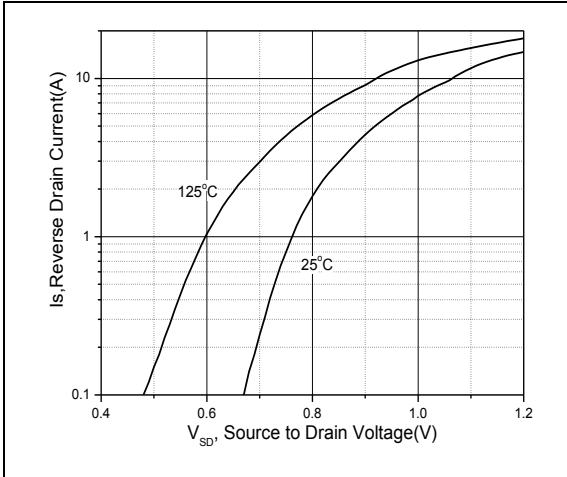


Figure 7. I_S - V_{SD}

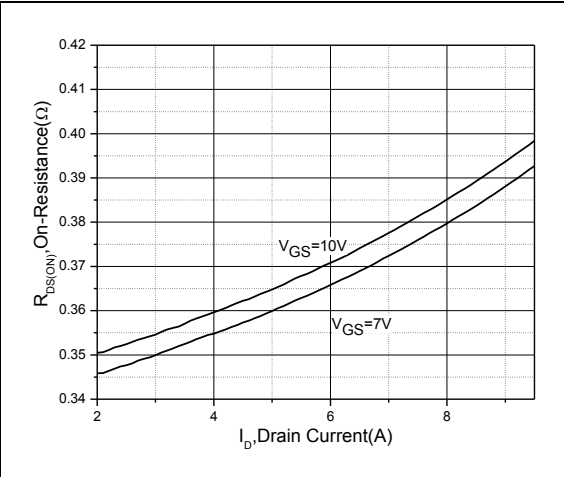


Figure 8. $R_{DS(ON)}$ - I_D

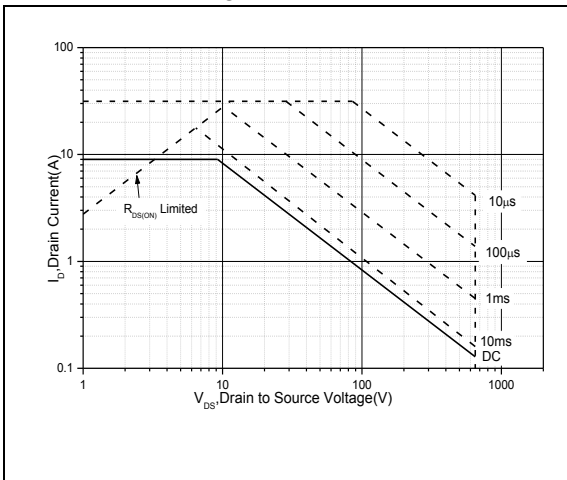


Figure 9. Safe Operation Area for TO251/TO252

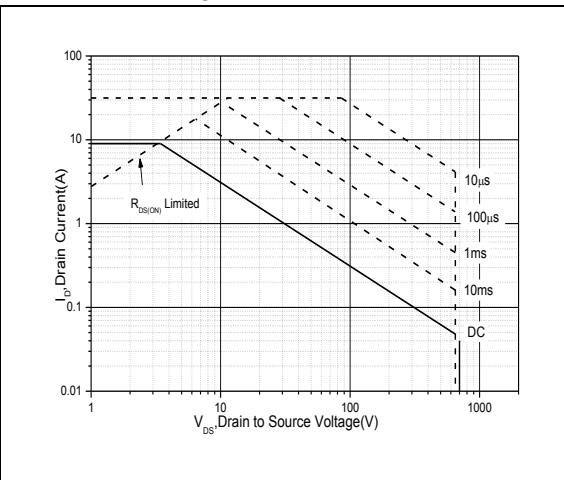


Figure 10. Safe Operation Area for TO220F

■ Test circuits and waveforms

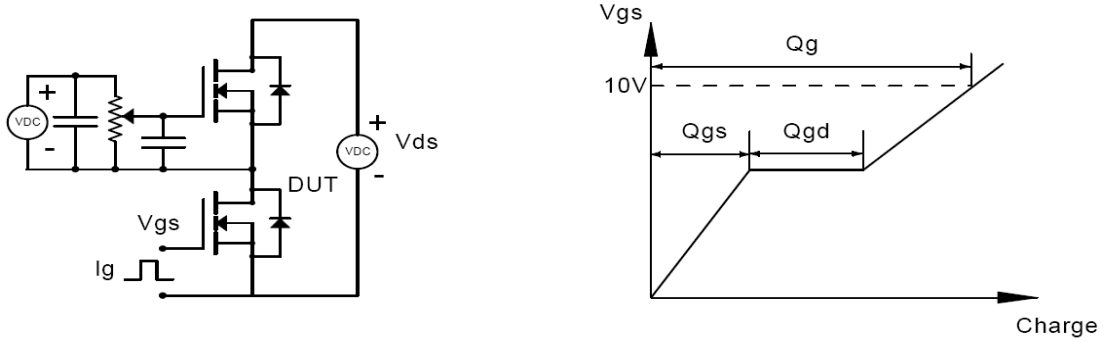


Figure 1, Gate Charge Test Circuit & Waveform

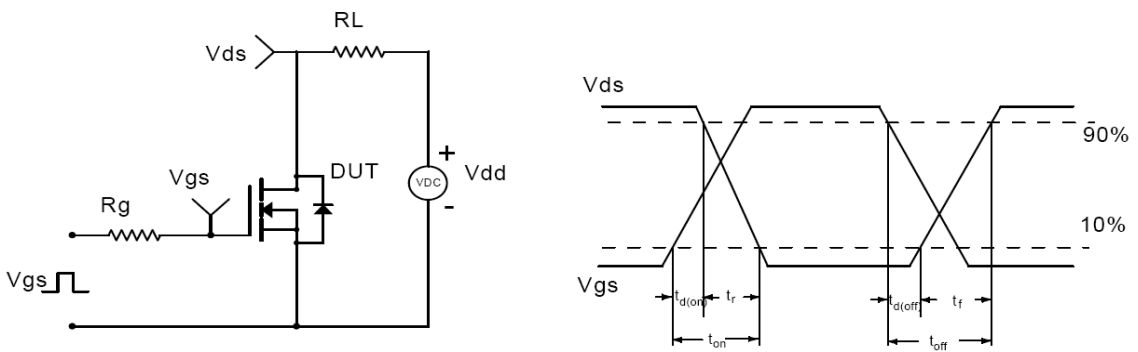


Figure 2, Resistive Switching Test Circuit & Waveforms

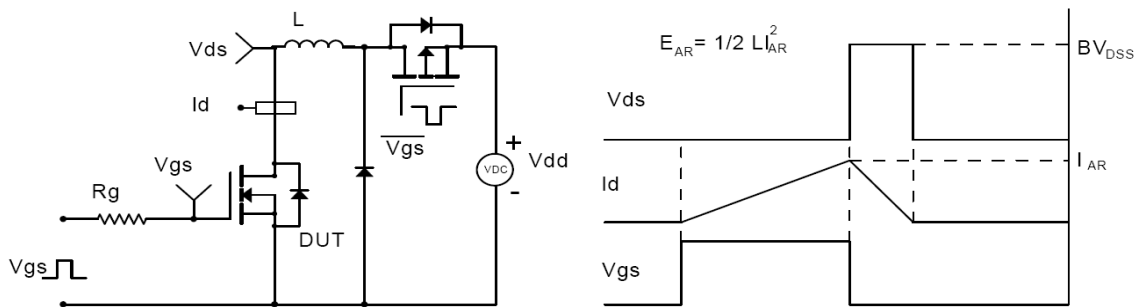


Figure 3, Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

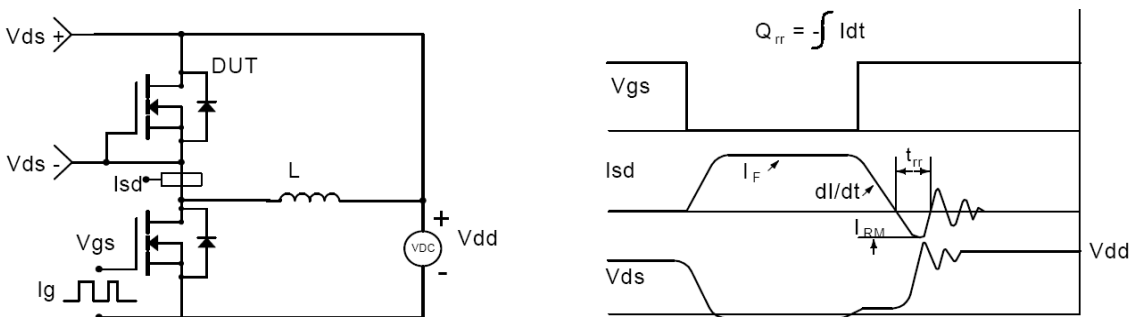
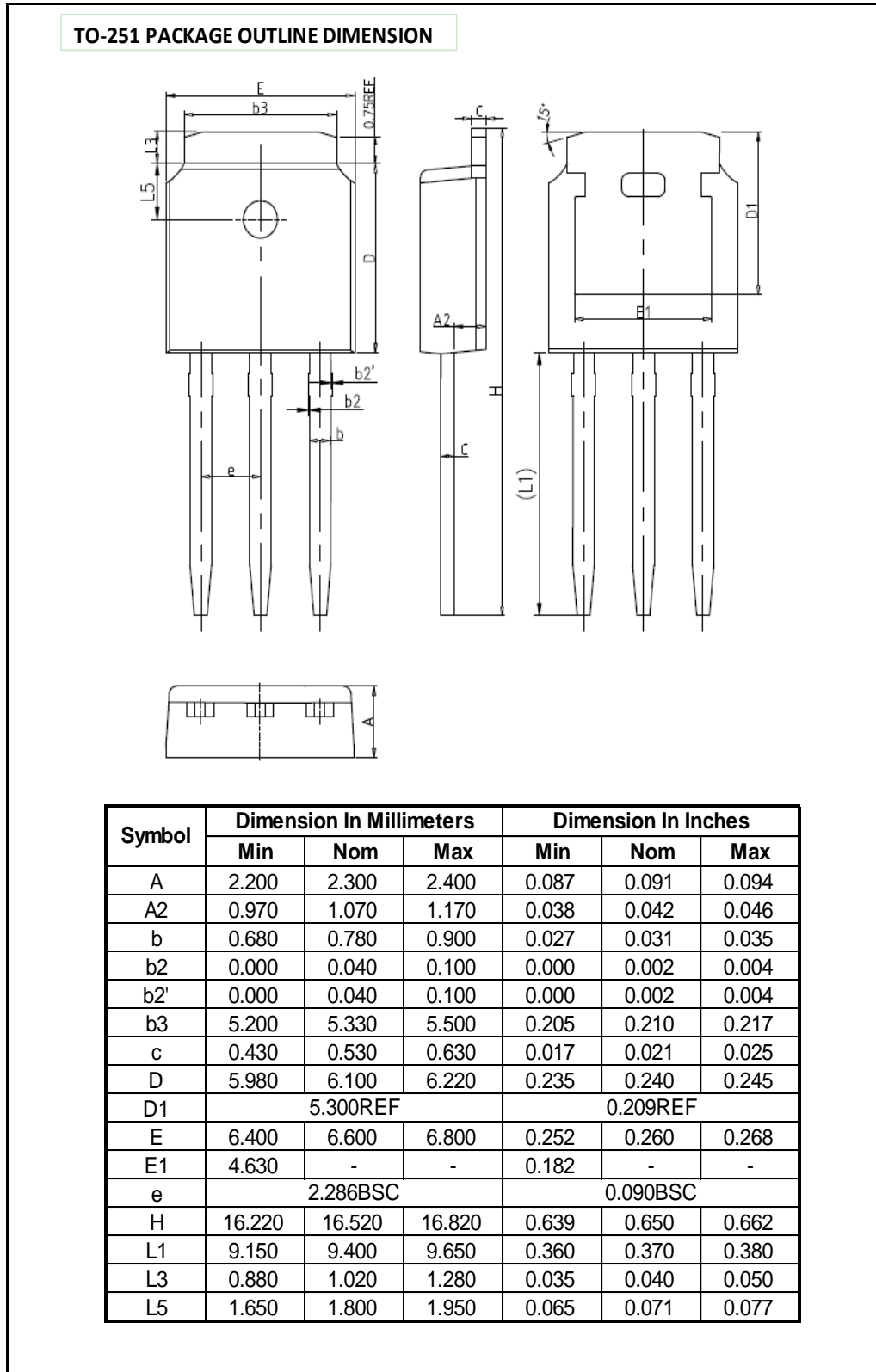


Figure 4, Diode Recovery Test Circuit & Waveforms

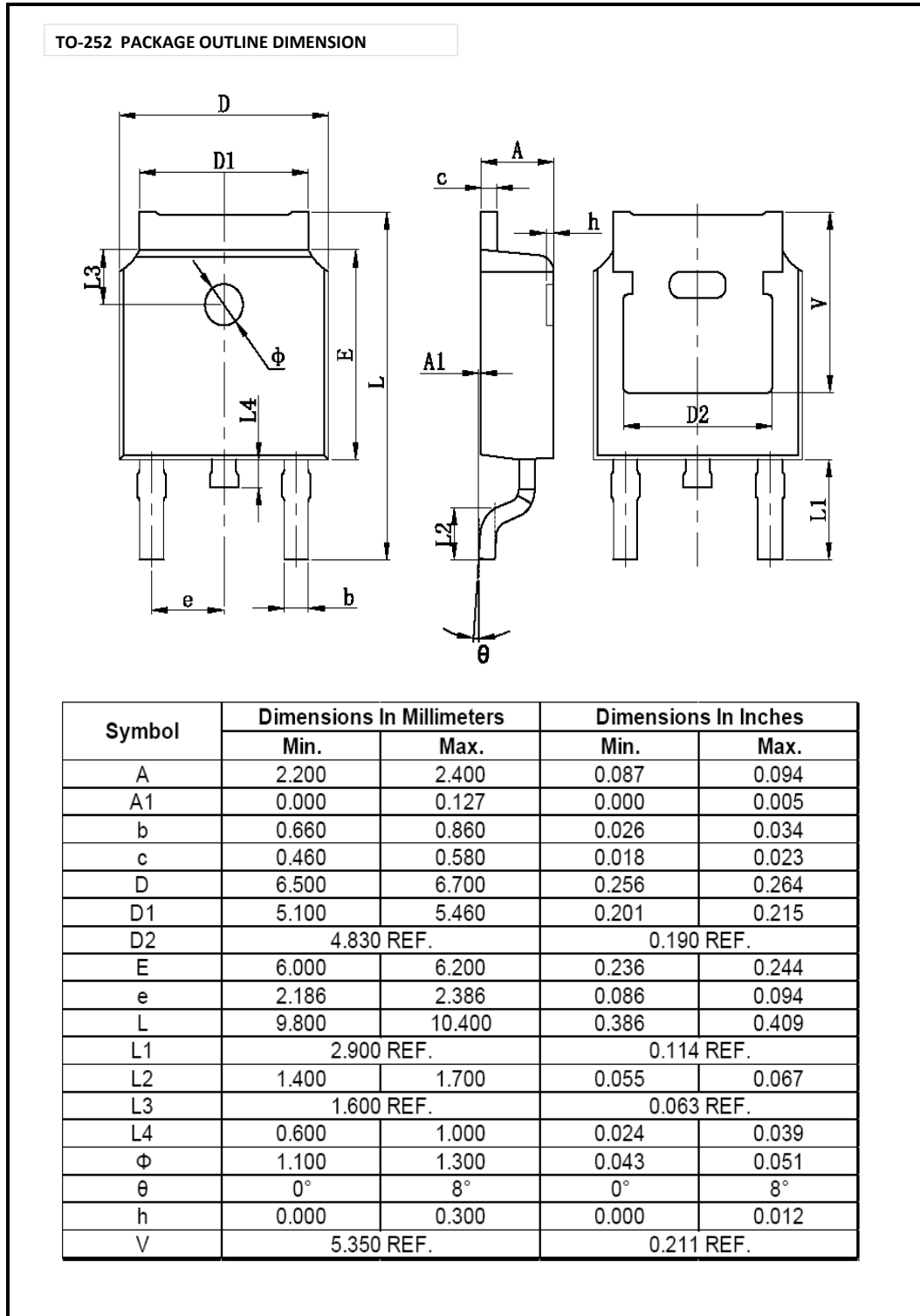
■ Package Information

Figure1



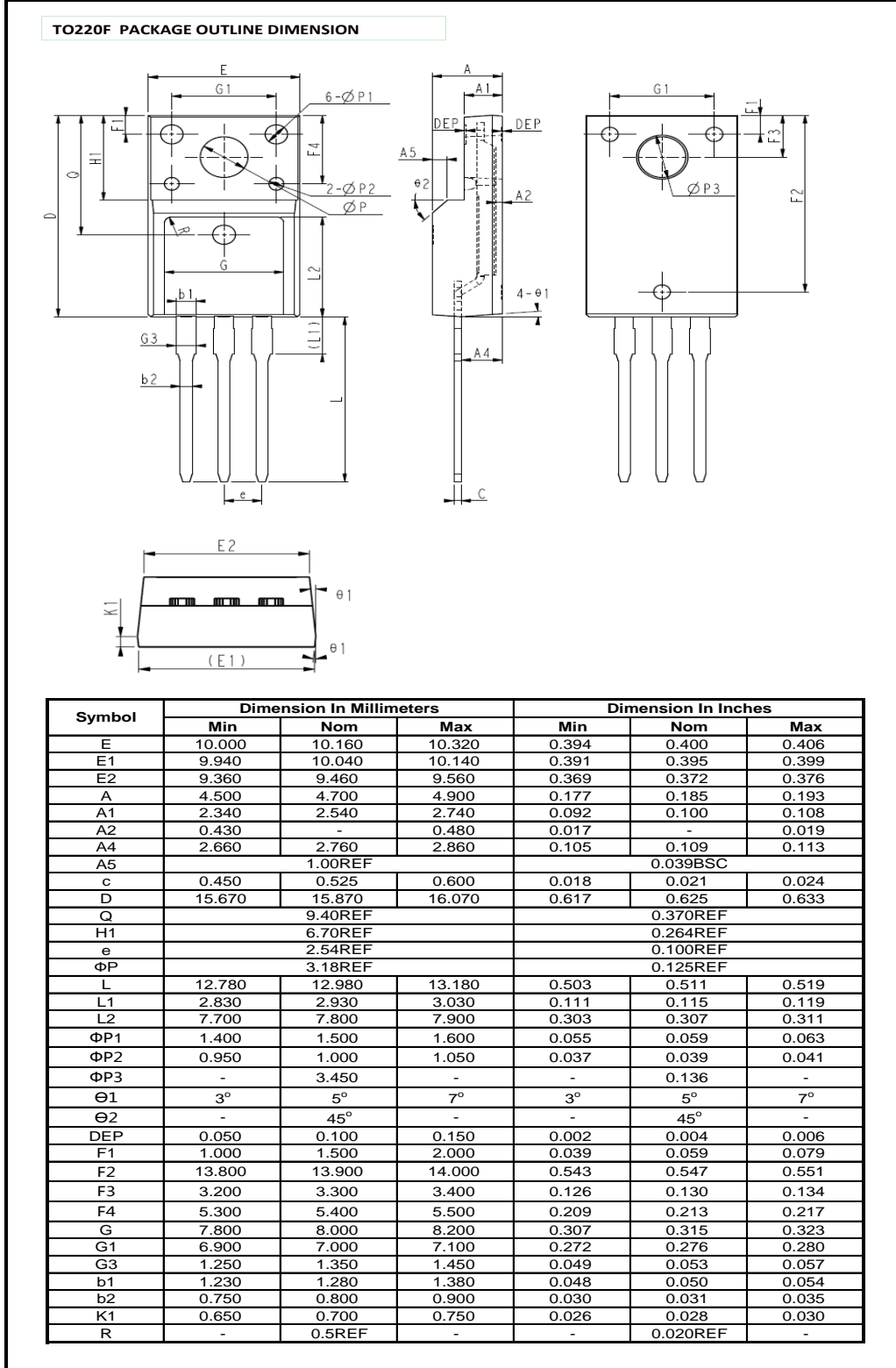
■ Package Information

Figure2



■ Package Information

Figure3



■ Ordering Information

| Package | Units/Tube | Tubes/Inner Box | Units/Inner Box | Inner Box/Carton Box | Units/Carton Box |
|--------------------------|------------|-----------------|-----------------|----------------------|------------------|
| TO251 | 75 | 66 | 4950 | 6 | 29700 |
| TO252 ^{Option1} | 75 | 66 | 4950 | 6 | 29700 |
| TO220F | 50 | 20 | 1000 | 6 | 6000 |

| Package | Units/Tape | Tapes/Inner Box | Units/Inner Box | Inner Box/Carton Box | Units/Carton Box |
|--------------------------|------------|-----------------|-----------------|----------------------|------------------|
| TO252 ^{Option2} | 2500 | 2 | 5000 | 5 | 25000 |

■ Note

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. P_D is based on max. junction temperature, using junction-to-case thermal resistance.
4. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_j = 25^\circ\text{C}$.
5. Declared by design, not subject to production.
6. $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, $L = 10.8\text{mH}$, Starting $T_j = 25^\circ\text{C}$.